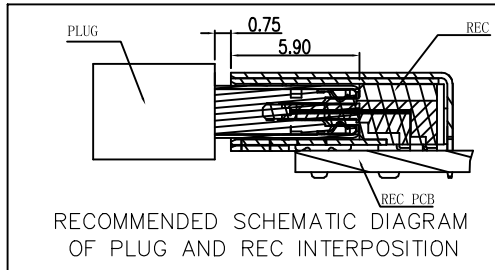
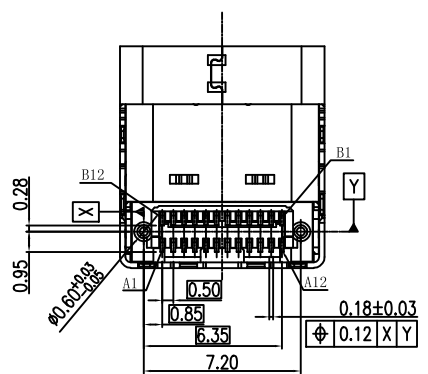
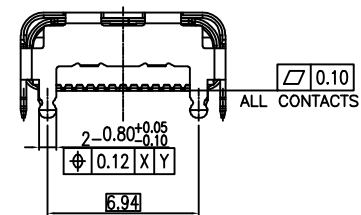
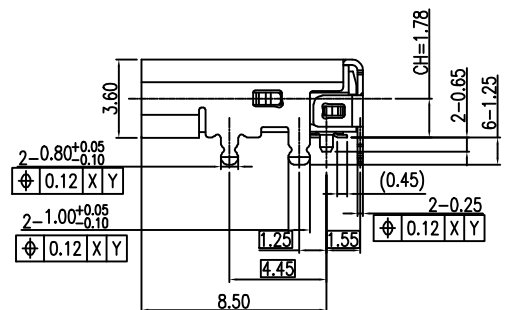
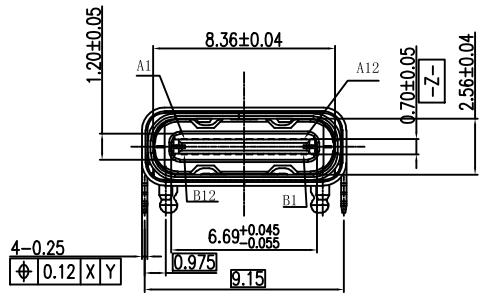
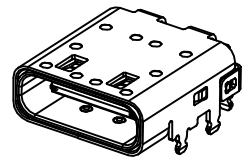
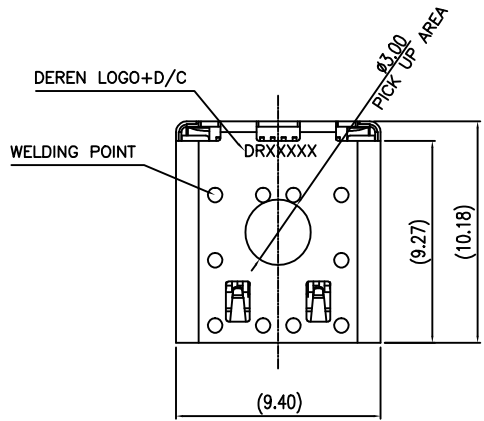


**HF**  
Halogen Free



RECOMMENDED SCHEMATIC DIAGRAM OF PLUG AND REC INTERPOSITION

DIM	TOL	DIM	TOL
.X	±0.30	.X	±3'
.X	±0.25	.X	±2'
.XX	±0.15		
.XXX	±0.10		

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			PRELIMINARY	11/30'20	Charles
X2			MODIFIED THE OUTER SHELL	12/25'20	Charles
X3			Change the appearance & Change carrier tape	02/01'20	Wenbin
X4			Add the size	06/08'20	Wenbin

- NOTES :
- ELECTRICAL :
    - CONTACT CURRENT RATING :
      - 5A FOR VBUS (Pins A4,A9,B4,B9),1.25A FOR VCONN.
      - 6.25A FOR GND (Pins A1,A12,B1,B12)
    - INSULATION RESISTANCE :
      - 100 MEGAOHMS. AT 300VDC.
    - DIELECTRIC WITHSTANDING VOLTAGE :100VAC, 0.5mA LEAKAGE CURRENT MAX..
    - LOW LEVEL CONTACT RESISTANCE :
      - INITIAL 40mΩ MAX. AFTER LIFE 50mΩ MAX.
  - MECHANICAL CHARACTERISTICS :
    - INSERTION FORCE : 5N~20N .
    - EXTRACTION FORCE : 8N~20N FROM 1 TO 30 CYCLES. 6N~20N FROM 31 TO 10000 CYCLES.
    - DURABILITY : 10,000 MATING CYCLES.
    - OPERATING TEMPERATURE :-55°C TO +85°C
    - RECOMMENDED STENCIL THICKNESS: 0.12mm min.

ITEM	PART NAME	QTY	MATERIAL	REMARK
⑥	TOP CONTACT	1 SET	COPPER ALLOY	50μ" MIN. NI UNDER PLATING, 80μ" MIN. MATTE TIN PLATING ON SOLDER AREA.
⑤	BOTTOM CONTACT	1 SET	COPPER ALLOY	10μ" MIN. GOLD PLATING ON CONTACT AREA.
④	MID PLATE	1 PCS	STAINLESS	50μ" MIN. NI PLATING OVERALL.
③	HOUSING	1 PCS	LCP	COLOR BLACK;UL94V-0
②	INNER SHELL	1 PCS	STAINLESS	WATER CLEANING
①	OUTER SHELL	1 PCS	STAINLESS	50μ" MIN. NI PLATING OVERALL.

**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

INSPECTION DRAWING      DATE      TITLE: UC REC 24P R/A CH=1.78 DUAL SMT CONN.

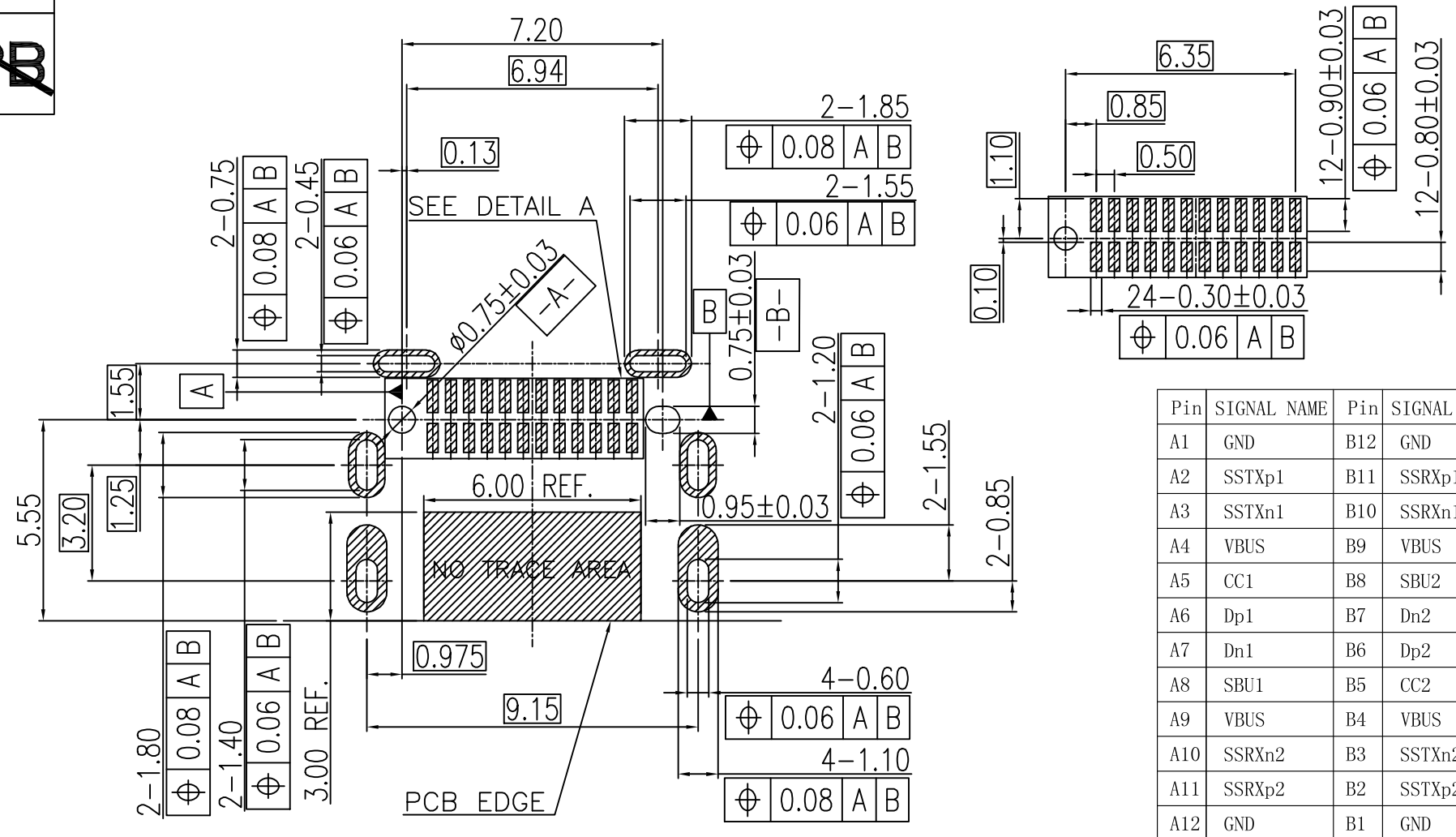
DESIGN: Wenbin      06/08'20      P/N: 5600B2-005H4000R

CHECK: Charles      06/08'20      SHEET: 1/3

REV. X4      APPROVAL: Smark      06/08'20      SCALE: 1:1      UNIT: mm



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					



Pin	SIGNAL NAME	Pin	SIGNAL NAME
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

DIM	TOL	DIM	TOL
X.	±0.30	X.	±3'
.X	±0.25	.X	±2'
.XX	±0.15		
.XXX	±0.10		

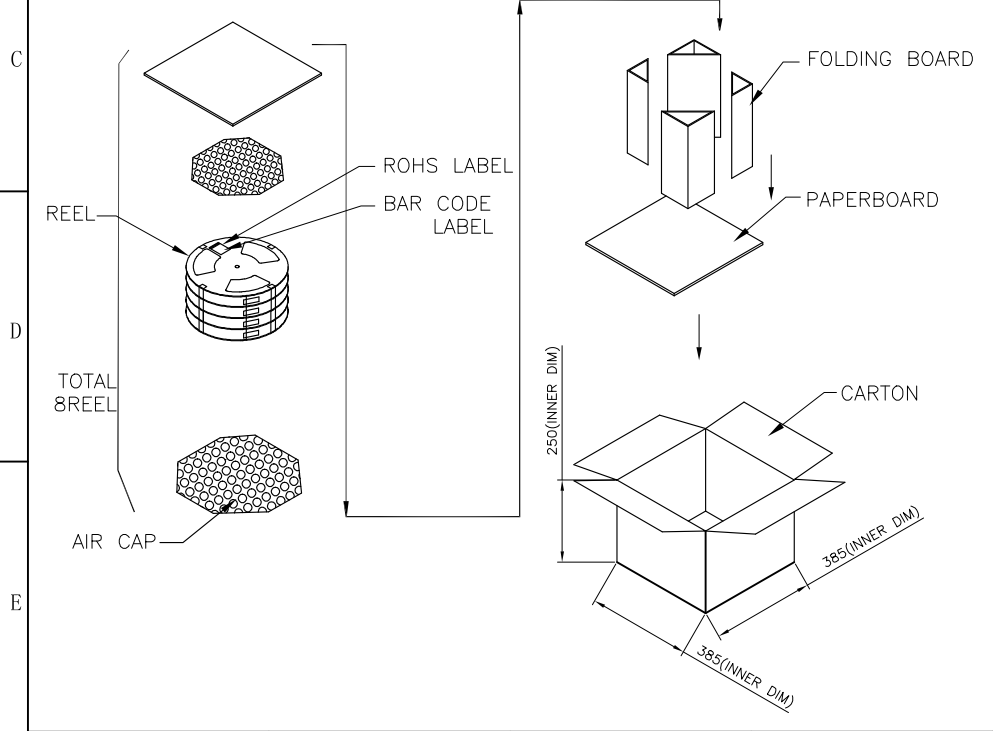
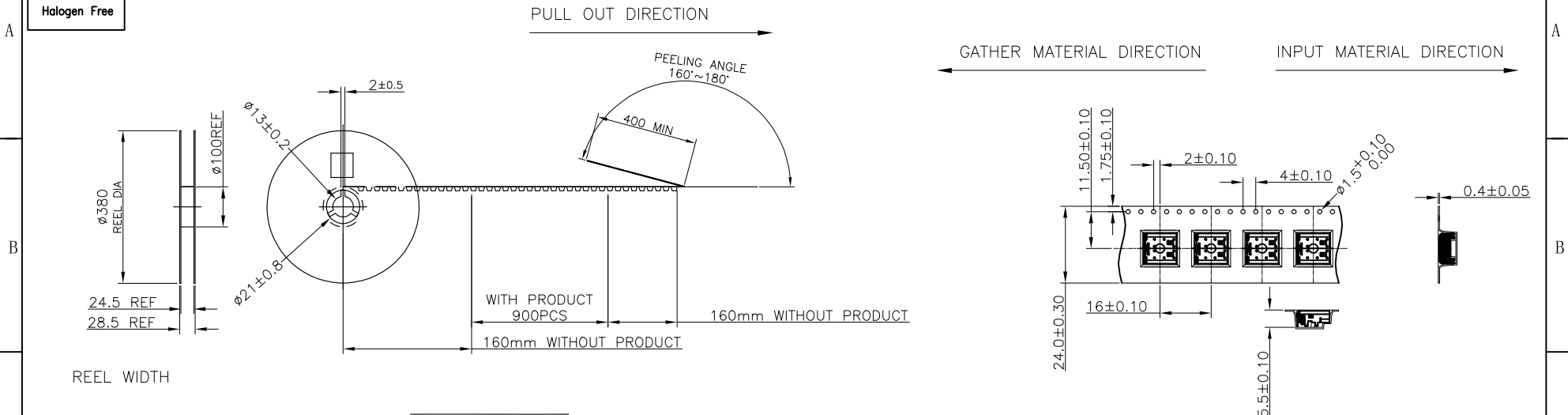
**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

INSPECTION DRAWING	DATE	TITLE: UC REC 24P R/A CH=1.78 DUAL SMT CONN.
DESIGN: Wenbin	06/08'20	P/N: 560QB2-005H4000R
CHECK: Charles	06/08'20	SHEET: 2/3
APPROVAL: Smark	06/08'20	SCALE: 1:1 UNIT: mm

DRAW NO. SC2007068  
REV. X4

**HF**  
Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					



NOTES :(FOR REEL)  
 PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0  
 PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT  
 MUST MEET CONTROLLED SUBSTANCES SPEC PER 230-702.  
 \* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED: 5 PPM.  
 \* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED: 100 PPM (COMBINED).  
 \* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS MUST MEET THE  
 REQUIREMENTS DEFINED PER EIA-481-B.

1. MATERIAL :  
 COVER TAPE : ANTISTATIC P.S T=0.05±0.01 ,COLOR: CLEAR  
 CARRIER TAPE : ANTISTATIC P.S T=0.40mm ±0.05  
 REEL : PS UL94V-0  
 SHIPPING BOX: CORRUGATED FIBER

2. DIMENSION :  
 REEL : SEE DRAWING  
 BOX : SEE DRAWING

3. QUANTITY : SEE TABLE

4. WEIGHT : SEE TABLE

5. PEELING RESISTANCE : 10gf~130gf (for 12~56mm)

6. PEELING SPEED : 300mm/MINUTES

900	8	7200	560QB2-005H4000R
PCS/ REEL	REEL/ BOX	PCS/ BOX	PART NUMBER

DIM		TOL		<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO.,LTD	CUSTOMER DRAWING		DATE		TITLE: UC REC 24P R/A CH=1.78 DUAL SMT CONN.	
x.	±0.30	x.	±2'		DRAW NO.	DESIGN:	Wenbin	06/08'20	P/N: 560QB2-005H4000R	
.x	±0.20	.x	±1'	SC2007068	CHECK:	Charles	06/08'20	SHEET: 3/3		
.xx	±0.10			REV. X4	APPROVAL:	Smark	06/08'20	SCALE: 1:1 UNIT: mm		